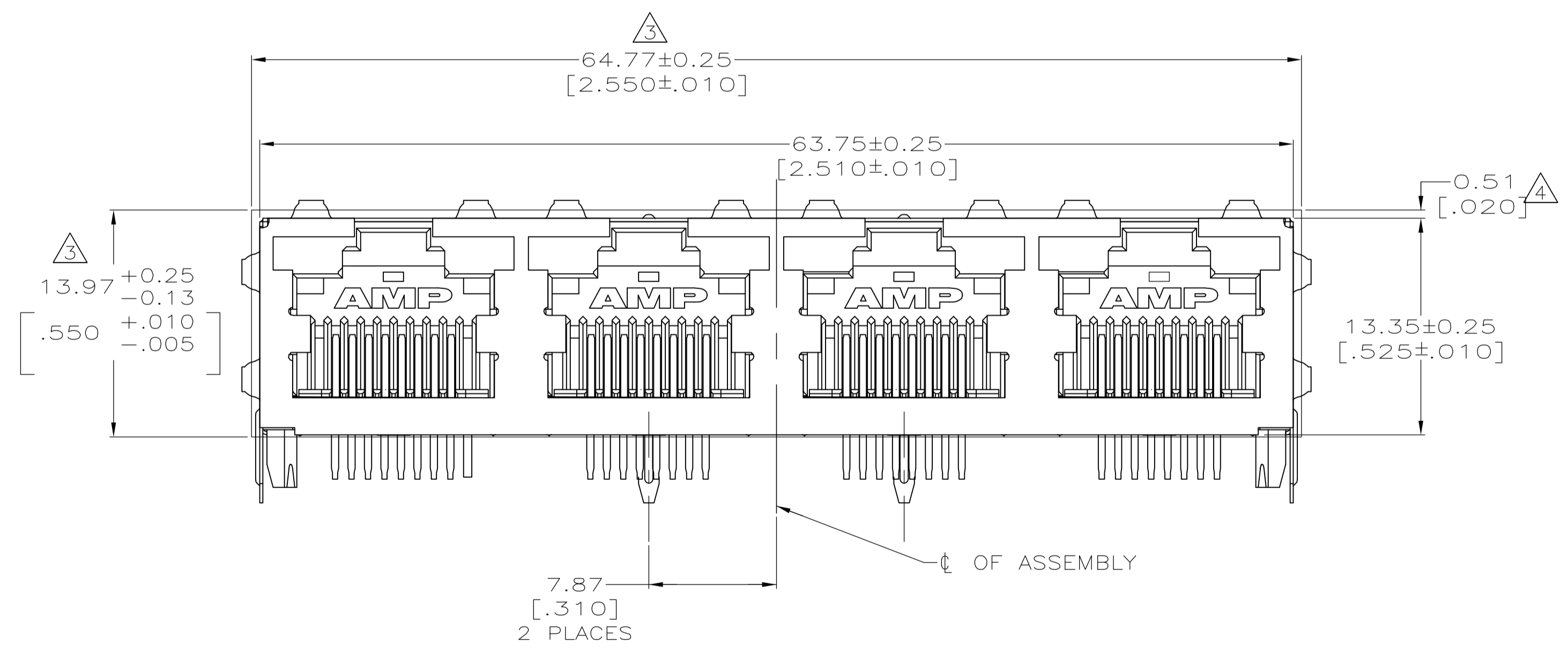
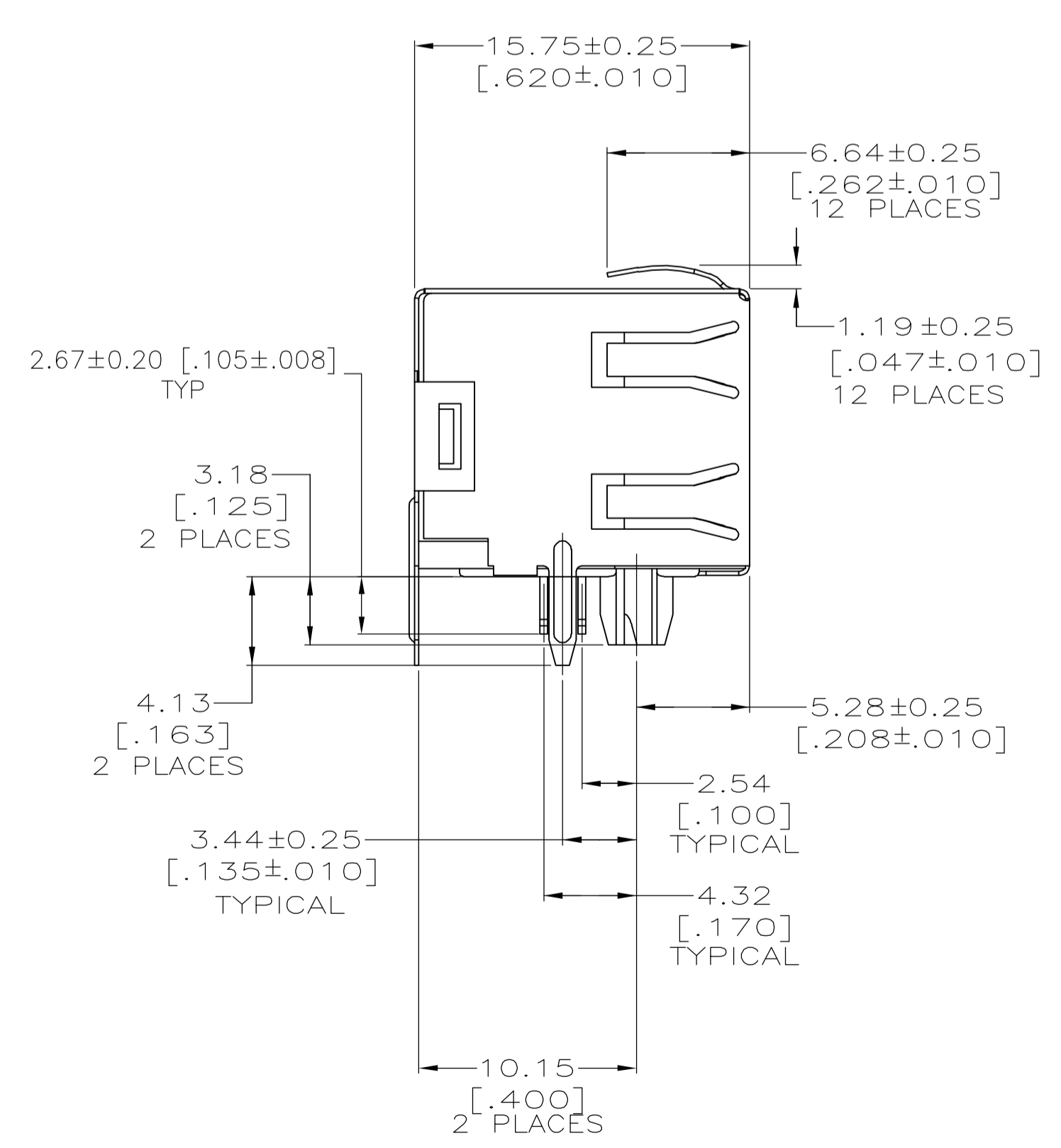


SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 0.7µm [.000030] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.
 SHIELD - .196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
 △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.

1888630-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN J. ALCORTA/L.A. MAYER 29AUG2006	Tyco Electronics Corporation Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 29AUG2006	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差		APVD S. FLICKINGER 29AUG2006	NAME: INVERTED MOD JACK ASSEMBLY, 1x4, SHIELDED, PANEL GROUND
0 PLC ± -		PRODUCT SPEC 108-1163-4	SIZE: A1
1 PLC ± -		APPLICATION SPEC 114-2154	SCALE: 4:1
2 PLC ± -		WEIGHT: -	SHEET 1 OF 1
3 PLC ± -		CUSTOMER DRAWING	REV B
4 PLC ± -			
ANGLES ± ± -			
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	100779	1888630